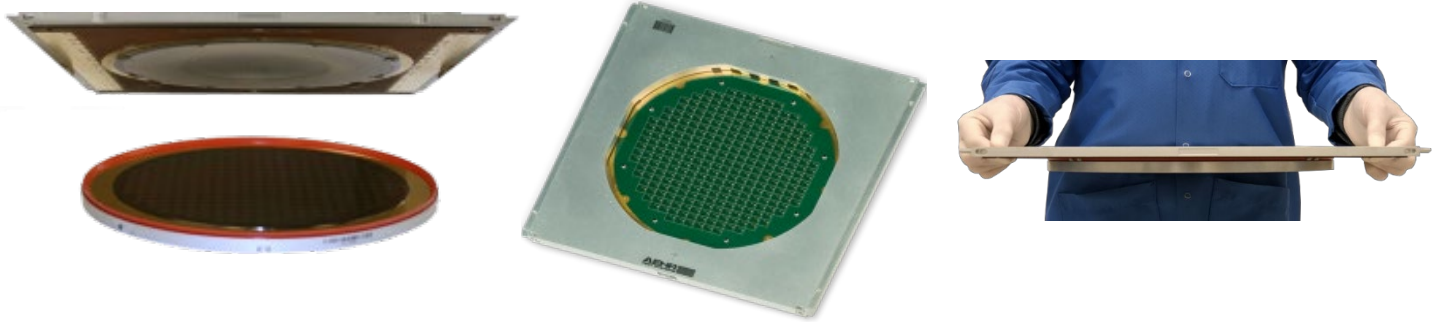


## FOX WaferPak Contactor

### Single Touchdown Full-Wafer Test & Burn-in



### PRODUCT BENEFITS

- **Delivers FOX system resources to the wafer enabling single touchdown test and burn-in**
  - ◆ Wafer sizes up to 300 mm
  - ◆ Production proven with > 60,000 contacts per wafer
  - ◆ Pad Metallurgy: Al, Cu, Au or solder balls
  - ◆ Temperature range: Ambient to 150° C
- **Supports up to 2,048 I/O and DPS channels with remote voltage and ground sense per pin**
  - ◆ Handles up to 4 amps per contact
- **Handles up to 2 kW of power dissipation**
- **Enables high volume full wafer production test and burn-in with one touchdown**
- **Field repairable**
- **Provides full wafer contact & alignment without a dedicated prober**
  - ◆ Signal Distribution Board (SDB) with multilayer design and onboard components
  - ◆ Ceramic Contactor CTE matched to the silicon wafer
  - ◆ Micro pogo pins with Flat, Rounded, Pointed, or Crown tips
  - ◆ ThinChuck provides thermal control of the wafer
  - ◆ Wafer is pre-aligned within the WaferPak Contactor then inserted into the FOX<sup>TM</sup> System

*“Setting the Test Standard for Tomorrow”*

#### CORPORATE HEADQUARTERS

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